Date:	01 Nov 2011
Product Category:	Memory
Device Family:	
Notification subject:	CCB 1072 Final Notice: Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as…
PCN_CYER-21JXDZ485_Affected_CPN.xls
PCN_CYER-21JXDZ485_Affected_CPN.pdf

Description of Change:
Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Pre Change:
8390A die attach

Post Change:
8006NS die attach

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 4, 2011 (date code: 1145)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
August 4, 2011: Issued initial notification.
November 1, 2011: Issued final notification. Added attached qualification report. Revised the estimated first ship date.

Attachment(s):

PCN_CYER-21JXDZ485_Affected_CPN.pdf PCN_CYER-21JXDZ485_Affected_CPN.xls
PCN_CYER-21JXDZ485_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Product Change Notification - CYER-21JXDZ485

PCN_CYER-21JXDZ485
CATALOG_PART_NBR
24AA1025-I/SM
24AA1025T-I/SM
24FC1025-I/SM
24FC1025T-I/SM
24LC1025-E/SM
24LC1025-I/SM
24LC1025T-E/SM
24LC1025T-I/SM

Parts Affected

24AA1025
24FC1025
24LC1025

QUALIFICATION REPORT
RELIABILITY LABORATORY

PCN#: CYER-21JXDZ485

Date
October 19, 2011

Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Distribution

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.
CN	BC112021
QUAL ID	Q11085
MP CODE	360037C3XA00
Part No.	24LC1025-I/SM
Bonding No.	BDE-001603 Rev. 02
CCB No.	1072
Package	
Type	8L SOIJ
Package size	208 mils
Die thickness	Bottom die 8 mils, Spacer 8 mils and Top die 8 mils
Die size	Bottom 114.3 x 109.5 mils, Top 114.3 x 109.5 mils
Spacer	75 x 94 x 8 mils
Lead Frame	
Paddle size	140 x 160 mils
Material	A194
Surface	Ag plate
Process	Stamp
Lead Lock	No
Part Number	10100816
Die attach material	
Epoxy	Top/ Bottom: 8390A, Spacer: 8006NS
Wire	Au wire
Mold Compound	G600V
Plating Composition	Matte Tin

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Trace Code
MTAI121803010	GRSM411501074.210	113193C
MTAI121803011	GRSM411501074.220	113193E
MTAI121803012	GRSM411501074.200	113193H

Result [X] Pass [ ] Fail [ ] ____________________

8L SOIJ (.208”) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020C standard.

Prepared By:______________________ **Date:** October 19, 2011 **(Reliability Engineer)**

(Mr.Thinnapol Nakkasun)

Approved By:____________________ **Date:** October 19, 2011 **(Reliability Manager)**

(Mr. Surasit Phurikhup)

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
MSL								
MSL Level 1/260°C	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 260°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020C)	S12/14/16 (PDC)	135	08/31/11	09/11/11	0/135	Pass	
Precondition								
Electrical Test	Electrical Test :+25°C and 85°C System: NEXTEST_PT (Test 1 lot 125°C on MTAI121803010.000)	S12/14/16 (PDC)	693(0)	08/20/11	08/26/11	693		Good Devices
Bake	Bake 150°C, 24 hrs System: CHINEE	PI-92014B		09/01/11	09/02/11	693		
Moisture Soak	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH	PI-91173B		09/02/11	09/09/11	693		
Convection-Reflow	3x Convection-Reflow 260°C max System: Vitronics Soltec MR1243	PI-91160B		09/09/11	09/09/11	693		
Electrical Test	Electrical Test :+25°C and 85°C System: NEXTEST_PT (Test 1 lot 125°C on MTAI121803010.000)	S12/14/16 (PDC)		09/10/11	09/11/11	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Qual Report : Q11085

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
Temp Cycle	**SAM Inspection:** (With 1 lot SAM on MTAI121803010.000)	PI-91081	10 (0)	09/114/11	09/14/11	10		
	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	PI-91020B		09/21/11	10/05/11	231		Parts had been pre-conditioned at 260°C
	Inspection: External crack inspection all units under 40X Optical magnification	QCI-33003	30(0)	10/05/11	10/05/11	0/30		
	SAM Inspection: (With 1 lot SAM on MTAI121803010.000)	PI-91081	10 (0)	10/05/11	10/11/11	10		
	Electrical Test: + 85°C System: NEXTEST_PT (Test 1 lot 125°C on MTAI121803010.000)	S12/14/16 (PDC)	231(0)	10/11/11	10/12/11	0/231	Pass	77 units / lot
	Bond Strength: Bond Shear (15.60 grams)	QCI-91022	15 (0)	10/13/11	10/13/11	0/15	Pass	
	Wire Pull (> 3 grams)		15 (0)	10/13/11	10/13/11	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	PI-91261B		09/12/11	09/16/11	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT	S12/14/16 (PDC)	231(0)	09/16/11	09/17/11	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Qual Report : Q11085

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	PI-92010B		09/14/11	09/19/11	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 85°C System: NEXTEST_PT (Test 1 lot 125°C on MTAI121803010.000)	S12/14/16 (PDC)	231(0)	09/19/11	09/20/11	0/231	Pass	77 units / lot
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs System: SHEL LAB	PI-92014B S12/14/16 (PDC)		09/01/11	09/20/11	45		45 units
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		45(0)	09/20/11	09/20/11	0/45	Pass	
Bond Strength **Data Assembly**	Bond Shear (15.60 grams)	QCI-91022	30 (0) bonds	-	-	0/30	Pass	
	Wire Pull (> 3 grams)		30 (0) wires	-	-	0/30	Pass	